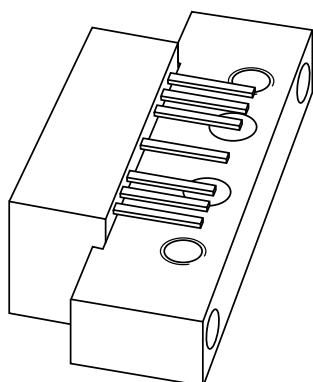


DATA SHEET



BGY887

860 MHz, 21.5 dB gain push-pull
amplifier

Product specification
Supersedes data of 1999 Mar 30

2001 Nov 15



860 MHz, 21.5 dB gain push-pull amplifier

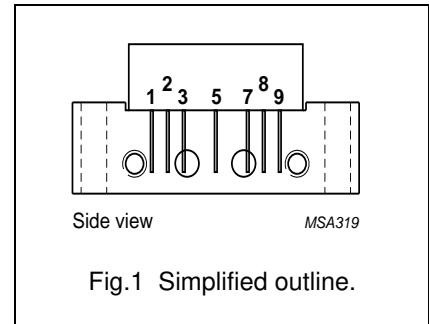
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FEATURES

- Excellent linearity
- Extremely low noise
- Excellent return loss properties
- Silicon nitride passivation
- Rugged construction
- Gold metallization ensures excellent reliability.

PINNING - SOT115J

PIN	DESCRIPTION
1	input
2	common
3	common
5	+V _B
7	common
8	common
9	output



APPLICATIONS

- CATV systems operating in the 40 to 860 MHz frequency range.

DESCRIPTION

Hybrid dynamic range amplifier module in a SOT115J package operating with a voltage supply of 24 V (DC).

QUICK REFERENCE DATA

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
G _p	power gain	f = 50 MHz	21	22	dB
		f = 860 MHz	21.5	–	dB
I _{tot}	total current consumption (DC)	V _B = 24 V	–	235	mA

LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	MIN.	MAX.	UNIT
V _i	RF input voltage	–	65	dBmV
T _{stg}	storage temperature	–40	+100	°C
T _{mb}	operating mounting base temperature	–20	+100	°C

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CHARACTERISTICS

Table 1 Bandwidth 40 to 860 MHz; $V_B = 24$ V; $T_{case} = 30$ °C; $Z_S = Z_L = 75$ Ω

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
G _p	power gain	f = 50 MHz	21	21.5	22	dB
		f = 860 MHz	21.5	22.5	–	dB
SL	slope cable equivalent	f = 40 to 860 MHz	0.2	1	2	dB
FL	flatness of frequency response	f = 40 to 860 MHz	–	±0.2	±0.3	dB
S ₁₁	input return losses	f = 40 to 80 MHz	20	29.5	–	dB
		f = 80 to 160 MHz	18.5	27.5	–	dB
		f = 160 to 320 MHz	17	23	–	dB
		f = 320 to 640 MHz	15.5	22	–	dB
		f = 640 to 860 MHz	14	20	–	dB
S ₂₂	output return losses	f = 40 to 80 MHz	20	27	–	dB
		f = 80 to 160 MHz	18.5	25	–	dB
		f = 160 to 320 MHz	17	20.5	–	dB
		f = 320 to 640 MHz	15.5	19	–	dB
		f = 640 to 860 MHz	14	19	–	dB
S ₂₁	phase response	f = 50 MHz	–45	–	+45	deg
CTB	composite triple beat	49 channels flat; V _o = 44 dBmV; measured at 859.25 MHz	–	–64.5	–62	dB
X _{mod}	cross modulation	49 channels flat; V _o = 44 dBmV; measured at 55.25 MHz	–	–64.5	–61	dB
CSO	composite second order distortion	49 channels flat; V _o = 44 dBmV; measured at 860.5 MHz	–	–67.5	–61	dB
d ₂	second order distortion	note 1	–	–77	–70	dB
V _o	output voltage	d _{im} = –60 dB; note 2	59	60.5	–	dBmV
F	noise figure	f = 50 MHz	–	4	4.5	dB
		f = 550 MHz	–	–	5	dB
		f = 600 MHz	–	–	5	dB
		f = 650 MHz	–	–	5	dB
		f = 750 MHz	–	–	5.5	dB
		f = 860 MHz	–	5	6.5	dB
I _{tot}	total current consumption (DC)	note 3	–	220	235	mA

Notes

- f_p = 55.25 MHz; V_p = 44 dBmV;
f_q = 805.25 MHz; V_q = 44 dBmV;
measured at f_p + f_q = 860.5 MHz.
- Measured according to DIN45004B:
f_p = 851.25 MHz; V_p = V_o;
f_q = 858.25 MHz; V_q = V_o –6 dB;
f_r = 860.25 MHz; V_r = V_o –6 dB;
measured at f_p + f_q – f_r = 849.25 MHz.
- The module normally operates at V_B = 24 V, but is able to withstand supply transients up to 30 V.

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Table 2 Bandwidth 40 to 860 MHz; $V_B = 24$ V; $T_{case} = 30$ °C; $Z_S = Z_L = 75 \Omega$

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
G _p	power gain	f = 50 MHz	21	21.5	22	dB
		f = 860 MHz	21.5	22.5	–	dB
SL	slope cable equivalent	f = 40 to 860 MHz	0.2	1	2	dB
FL	flatness of frequency response	f = 40 to 860 MHz	–	±0.2	±0.3	dB
S ₁₁	input return losses	f = 40 to 80 MHz	20	29.5	–	dB
		f = 80 to 160 MHz	18.5	27.5	–	dB
		f = 160 to 320 MHz	17	23	–	dB
		f = 320 to 640 MHz	15.5	22	–	dB
		f = 640 to 860 MHz	14	20	–	dB
S ₂₂	output return losses	f = 40 to 80 MHz	20	27	–	dB
		f = 80 to 160 MHz	18.5	25	–	dB
		f = 160 to 320 MHz	17	20.5	–	dB
		f = 320 to 640 MHz	15.5	19	–	dB
		f = 640 to 860 MHz	14	19	–	dB
S ₂₁	phase response	f = 50 MHz	–45	–	+45	deg
CTB	composite triple beat	129 channels flat; V _o = 42 dBmV; measured at 859.25 MHz	–	–54	–51	dB
X _{mod}	cross modulation	129 channels flat; V _o = 42 dBmV; measured at 55.25 MHz	–	–60	–57	dB
CSO	composite second order distortion	129 channels flat; V _o = 42 dBmV; measured at 860.5 MHz	–	–60.5	–55	dB
d ₂	second order distortion	note 1	–	–77	–70	dB
V _o	output voltage	d _{im} = –60 dB; note 2	59	60.5	–	dBmV
F	noise figure	see Table 1	–	–	–	dB
I _{tot}	total current consumption (DC)	note 3	–	220	235	mA

Notes

1. f_p = 55.25 MHz; V_p = 44 dBmV;
f_q = 805.25 MHz; V_q = 44 dBmV;
measured at f_p + f_q = 860.5 MHz.
2. Measured according to DIN45004B:
f_p = 851.25 MHz; V_p = V_o;
f_q = 858.25 MHz; V_q = V_o –6 dB;
f_r = 860.25 MHz; V_r = V_o –6 dB;
measured at f_p + f_q – f_r = 849.25 MHz.
3. The module normally operates at V_B = 24 V, but is able to withstand supply transients up to 30 V.

860 MHz, 21.5 dB gain push-pull amplifier

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Table 3 Bandwidth 40 to 750 MHz; $V_B = 24$ V; $T_{case} = 30$ °C; $Z_S = Z_L = 75 \Omega$

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
G _p	power gain	f = 50 MHz	21	21.5	22	dB
		f = 750 MHz	21.5	22.3	–	dB
SL	slope cable equivalent	f = 40 to 750 MHz	0.2	–	2	dB
FL	flatness of frequency response	f = 40 to 750 MHz	–	–	±0.3	dB
S ₁₁	input return losses	f = 40 to 80 MHz	20	29.5	–	dB
		f = 80 to 160 MHz	18.5	27.5	–	dB
		f = 160 to 320 MHz	17	23	–	dB
		f = 320 to 640 MHz	15.5	22	–	dB
		f = 640 to 750 MHz	14	20	–	dB
S ₂₂	output return losses	f = 40 to 80 MHz	20	27	–	dB
		f = 80 to 160 MHz	18.5	25	–	dB
		f = 160 to 320 MHz	17	20.5	–	dB
		f = 320 to 640 MHz	15.5	19	–	dB
		f = 640 to 750 MHz	14	19	–	dB
S ₂₁	phase response	f = 50 MHz	–45	–	+45	deg
CTB	composite triple beat	110 channels flat; V _o = 44 dBmV; measured at 745.25 MHz	–	–53	–51	dB
X _{mod}	cross modulation	110 channels flat; V _o = 44 dBmV; measured at 55.25 MHz	–	–57	–54	dB
CSO	composite second order distortion	110 channels flat; V _o = 44 dBmV; measured at 746.5 MHz	–	–62	–56	dB
d ₂	second order distortion	note 1	–	–78	–70	dB
V _o	output voltage	d _{im} = –60 dB; note 2	60	62	–	dBmV
F	noise figure	see Table 1	–	–	–	dB
I _{tot}	total current consumption (DC)	note 3	–	220	235	mA

Notes

1. $f_p = 55.25$ MHz; $V_p = 44$ dBmV;
 $f_q = 691.25$ MHz; $V_q = 44$ dBmV;
measured at $f_p + f_q = 746.5$ MHz.
2. Measured according to DIN45004B:
 $f_p = 740.25$ MHz; $V_p = V_o$;
 $f_q = 747.25$ MHz; $V_q = V_o - 6$ dB;
 $f_r = 749.25$ MHz; $V_r = V_o - 6$ dB;
measured at $f_p + f_q - f_r = 738.25$ MHz.
3. The module normally operates at $V_B = 24$ V, but is able to withstand supply transients up to 30 V.

860 MHz, 21.5 dB gain push-pull amplifier

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Table 4 Bandwidth 40 to 600 MHz; $V_B = 24$ V; $T_{case} = 30$ °C; $Z_S = Z_L = 75 \Omega$

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
G _p	power gain	f = 50 MHz	21	21.5	22	dB
		f = 600 MHz	21.5	22.1	–	dB
SL	slope cable equivalent	f = 40 to 600 MHz	0.2	–	2	dB
FL	flatness of frequency response	f = 40 to 600 MHz	–	–	±0.2	dB
S ₁₁	input return losses	f = 40 to 80 MHz	20	29.5	–	dB
		f = 80 to 160 MHz	18.5	27.5	–	dB
		f = 160 to 320 MHz	17	23	–	dB
		f = 320 to 600 MHz	16	22	–	dB
S ₂₂	output return losses	f = 40 to 80 MHz	20	27	–	dB
		f = 80 to 160 MHz	18.5	25	–	dB
		f = 160 to 320 MHz	17	20.5	–	dB
		f = 320 to 600 MHz	16	19	–	dB
S ₂₁	phase response	f = 50 MHz	–45	–	+45	deg
CTB	composite triple beat	85 channels flat; V _o = 44 dBmV; measured at 595.25 MHz	–	–	–56	dB
X _{mod}	cross modulation	85 channels flat; V _o = 44 dBmV; measured at 55.25 MHz	–	–	–57	dB
CSO	composite second order distortion	85 channels flat; V _o = 44 dBmV; measured at 596.5 MHz	–	–	–58	dB
d ₂	second order distortion	note 1	–	–	–70	dB
V _o	output voltage	d _{im} = –60 dB; note 2	61	–	–	dBmV
F	noise figure	see Table 1	–	–	–	dB
I _{tot}	total current consumption (DC)	note 3	–	220	235	mA

Notes

1. $f_p = 55.25$ MHz; $V_p = 44$ dBmV;
 $f_q = 541.25$ MHz; $V_q = 44$ dBmV;
measured at $f_p + f_q = 596.5$ MHz.
2. Measured according to DIN45004B:
 $f_p = 590.25$ MHz; $V_p = V_o$;
 $f_q = 597.25$ MHz; $V_q = V_o - 6$ dB;
 $f_r = 599.25$ MHz; $V_r = V_o - 6$ dB;
measured at $f_p + f_q - f_r = 588.25$ MHz.
3. The module normally operates at $V_B = 24$ V, but is able to withstand supply transients up to 30 V.

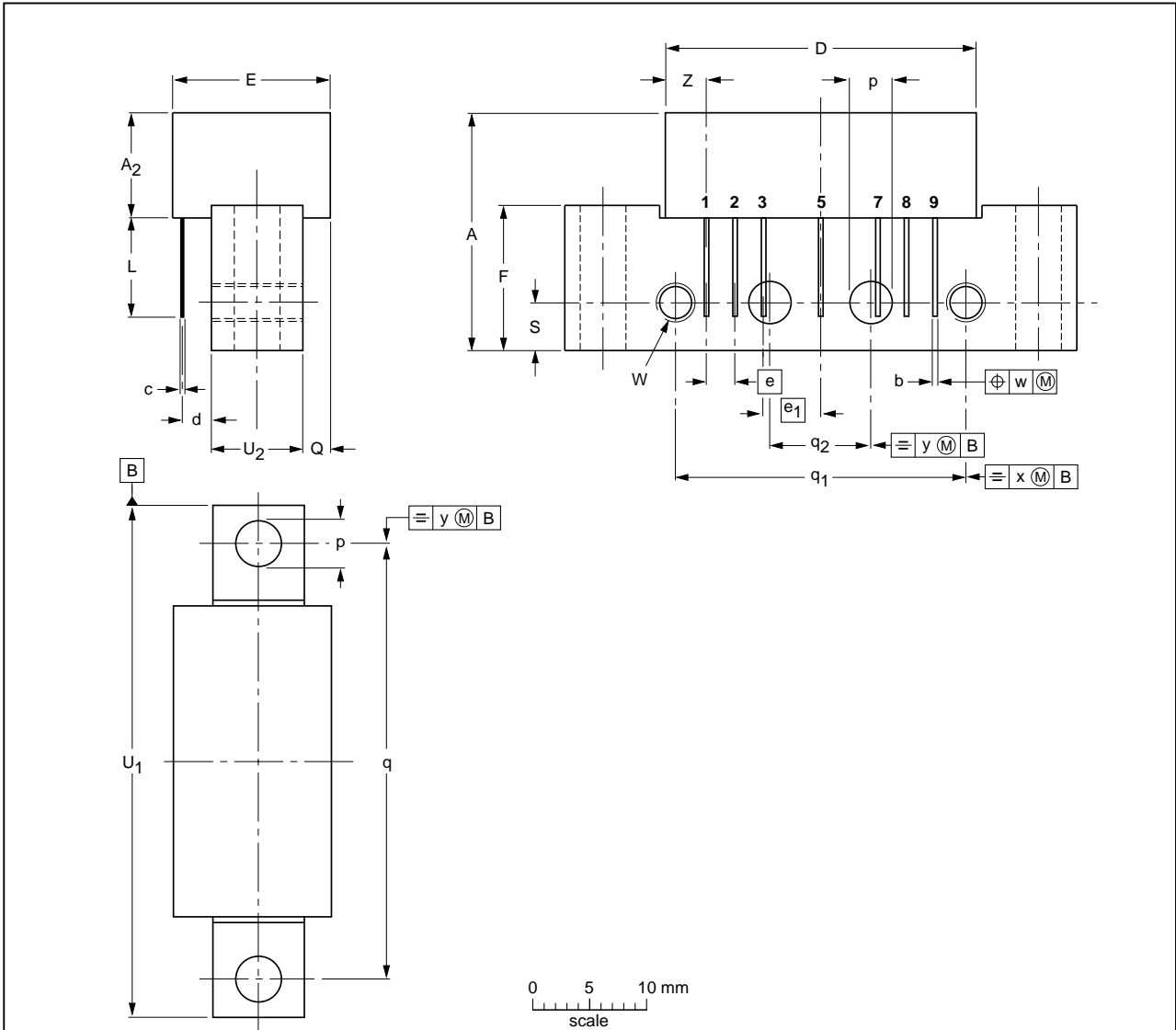
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PACKAGE OUTLINE

Rectangular single-ended package; aluminium flange; 2 vertical mounting holes; 2 x 6-32 UNC and 2 extra horizontal mounting holes; 7 gold-plated in-line leads

SOT115J



DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A ₂ max.	b	c	D max.	d	E max.	e	e ₁	F	L min.	p	Q max.	q	q ₁	q ₂	S	U ₁	U ₂	W	w	x	y	Z max.
mm	20.8	9.5	0.51 0.38	0.25	27.2	2.04 2.54	13.75	2.54	5.08	12.7	8.8	4.15 3.85	2.4	38.1	25.4	10.2	4.2	44.75 44.25	8.2 7.8	6-32 UNC	0.25	0.7	0.1	3.8

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT115J						04-02-04 10-06-18

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DATA SHEET STATUS

DOCUMENT STATUS ⁽¹⁾	PRODUCT STATUS ⁽²⁾	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
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Contact information

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